

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSZ035N03LS G	**Issued**	06. April 2021
MA#	MA001684524		
Package	PG-TSDSON-8-2	**Weight***	40.20 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.836	4.57	4.57	45675	45675
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		52	
	non noble metal	zinc	7440-66-6	0.008	0.02		209	
	non noble metal	iron	7439-89-6	0.168	0.42		4170	
	non noble metal	copper	7440-50-8	6.808	16.93	17.38	169327	173758
wire	non noble metal	copper	7440-50-8	0.036	0.09	0.09	896	896
encapsulation	organic material	carbon black	1333-86-4	0.037	0.09		909	
	plastics	epoxy resin	-	1.882	4.68		46818	
	inorganic material	silicondioxide	60676-86-0	16.356	40.70	45.47	406817	454544
leadfinish	non noble metal	tin	7440-31-5	0.387	0.96	0.96	9629	9629
plating	noble metal	silver	7440-22-4	0.963	2.39	2.39	23942	23942
solder	non noble metal	tin	7440-31-5	0.037	0.09		916	
	noble metal	silver	7440-22-4	0.046	0.11		1145	
	non noble metal	lead	7439-92-1	1.759	4.37	4.57	43743	45804
heatspreader	inorganic material	phosphorus	7723-14-0	0.001			27	
	non noble metal	zinc	7440-66-6	0.004	0.01		107	
	non noble metal	iron	7439-89-6	0.086	0.21		2145	
	non noble metal	copper	7440-50-8	3.501	8.71	8.93	87084	89363
heat sink CLIP	inorganic material	phosphorus	7723-14-0	0.002			47	
	non noble metal	zinc	7440-66-6	0.008	0.02		188	
	non noble metal	iron	7439-89-6	0.151	0.38		3753	
	non noble metal	copper	7440-50-8	6.127	15.24	15.64	152401	156389
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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